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AMENDMENT TO THE SPECIFICATION

Please replace the paragraph beginning on page 14, line 30 as follows.

To form the sliders with the thermal transducers located on the air bearing surface (e.g. raised bearing surfaces), a plurality of thermal transducers 500 can be applied along the smooth surface 502 of wafer 504, as shown in Fig. 8. Thermal transducers 500 are located or formed on the raised bearing surfaces 508 of rails 506 contoured onto surface 502 or contoured surface to form a surface portion 509 extending along a portion of the raised surface 508 of rail 506 and a thickness portion 514 which forms a profile 518 of the contoured surface as illustrated in Fig. 10. Representative rails 506 are noted in Fig. 8. Alternatively, as previously explained, thermal transducers 500 can be formed on the raised contoured surface or rails of the air bearing surface on a bar sliced from the wafer. As shown in FIG. 10, the thermal transducers 500 can be covered with a protective layer 516, such as diamond-like carbon. Additional transducers such as a piezoelectric transducer also can be placed on the opposite surface of the wafer prior to the slicing into individual sliders.